Special Issue

Material Interconnections and Microstructure Control-Related

Message from the Guest Editor

The advancement of electronic devices requires new interconnection materials, which should possess excellent electric/thermal conductivity as well as high robustness. New interconnection materials/technologies and their control methods must be established based on scientific understanding of hetero-interface phenomena. This Special Issue will focus on the current researches in interconnections and their microstructural control for advancing electronic devices, including soldering, sinter joining, conductive adhesive, alternative interconnects, metallization, substrates, 3D packaging, quality, reliability, and failure analysis. We will assess how certain interconnect features (device metallization, interconnects, substrates, design, etc.) can influence the performance and reliability of devices. Your contributions will provide considerable impact on new electronic/optical devices. Prof. Katsuaki Suganuma

Guest Editor

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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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